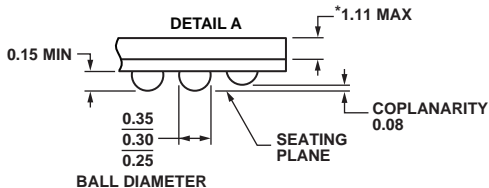
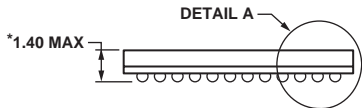
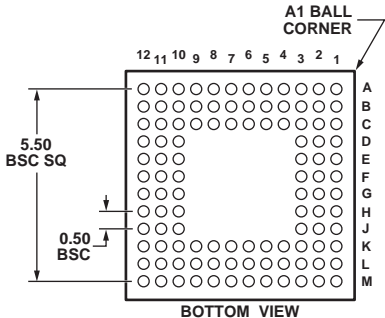
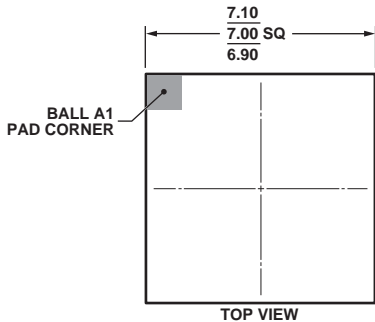


**108-Ball Chip Scale Package Ball Grid Array [CSP_BGA]
(BC-108-4)**

Dimensions shown in millimeters



*COMPLIANT WITH JEDEC STANDARDS MO-195-BD WITH
EXCEPTION TO PACKAGE HEIGHT AND THICKNESS.